

Common Mode Filter 1.2x1.0mm

SIC04-41 series

MERITEK

FEATURE

- Common Mode Filter For Large Current Applications
- Excellent Impedance Characteristics for Noise Suppression
- Low Profile Construction Design
- Application: High-Density Portable Devices, Personal Computers, Display Panels, DC Power Lines and Automotive Power Trains



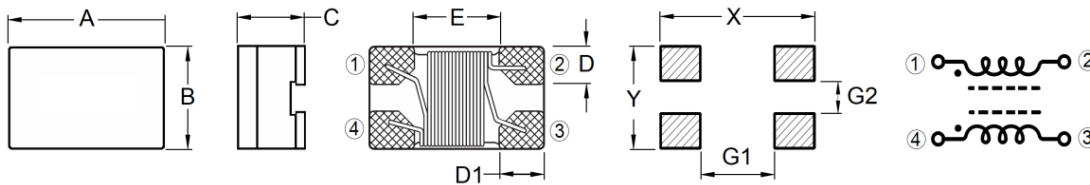
ELECTRICAL CHARACTERISTICS

Part Number	Common Mode Impedance (Ω)	Test Frequency (MHz)	DCR Max (m Ω)	Rated Current (mA)	Rated Voltage (Vdc)	IR Min (M Ω)	Withstand Voltage (Vdc)
SIC04161A1641	160 \pm 25%	100	430	160	50	10	125
SIC04201A1241	200 \pm 25%	100	800	120	50	10	125

Notes:

1. All test data referenced to 25°C ambient.
2. Operating Temperature: -40°C ~ +105°C (Including Self-temperature rise)

DIMENSIONS



Unit: mm

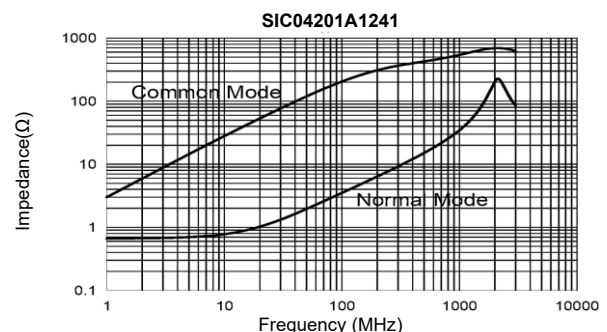
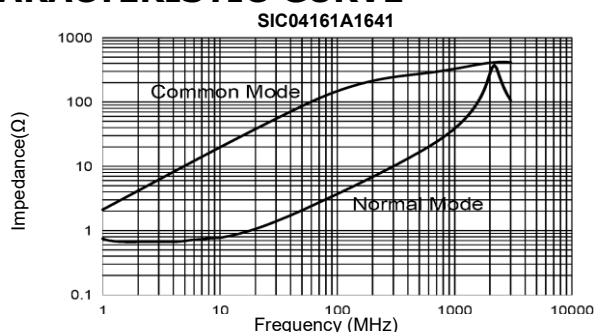
Size Code	A \pm 0.2	B \pm 0.2	C \pm 0.2	D \pm 0.1	D1 \pm 0.1	E Typ	X	Y	G1	G2
04 (0504)	1.2	1.00	0.9	0.35	0.35	0.5	1.5	1.2	0.6	0.3

PART NUMBERING SYSTEM

SIC **04** **201** **A12** **41**
(1) (2) (3) (4) (5)

No	Item	Code	Description
(1)	Product Code	SIC	Surface Mount Inductor, Common Mode Choke type
(2)	Dimension Code	04	04: 0504 1.2 X 1.0mm, L x W (mm)
(3)	Impedance	201	200 Ω First two digits: significant, Third: Multiplier
(4)	Rated Current	A12	0.12A A: Decimal
(5)	Series Code	41	Common Mode Filter, for Power Line

CHARACTERISTIC CURVE

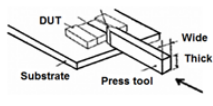
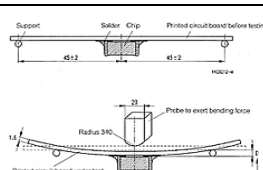


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RELIABILITY TEST CONDITON AND REQUIREMENT

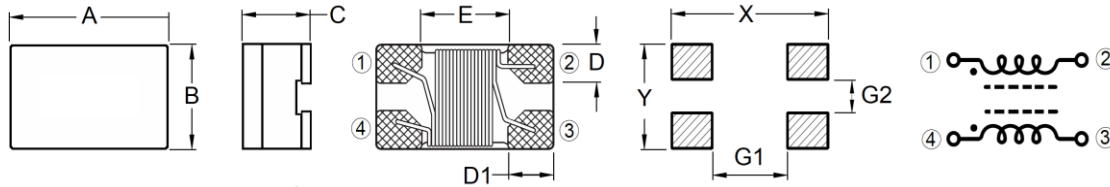
Item	Test Standards / Conditions / Equipment	Requirement															
Impedance	Agilent-4291A, Agilent-16197A	Refer to specification															
DC Resistance	Agilent-4338B	Refer to specification															
I.R	Agilent-4339	Refer to specification															
Temperature Rise Test	1. Applied the allowed DC current 2. Temperature measured by digital surface thermometer	Rated Current < 1A : $\Delta T = 20^{\circ}\text{C}$ Max Rated Current $\geq 1\text{A}$: $\Delta T = 40^{\circ}\text{C}$ Max															
Mechanical Shock	<table border="1"> <thead> <tr> <th>Type</th> <th>Peak value (g's)</th> <th>Normal duration (D) (ms)</th> <th>Wave form</th> <th>Velocity change (Vi) ft/sec</th> </tr> </thead> <tbody> <tr> <td>SMD</td> <td>50</td> <td>11</td> <td>Half-sine</td> <td>11.3</td> </tr> <tr> <td>Lead</td> <td>50</td> <td>11</td> <td>Half-sine</td> <td>11.3</td> </tr> </tbody> </table>	Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi) ft/sec	SMD	50	11	Half-sine	11.3	Lead	50	11	Half-sine	11.3	Appearance: No damage Impedance: within $\pm 15\%$ of initial value Inductance: within $\pm 10\%$ of initial value Q: Shall not exceed the specification value RDC: within $\pm 15\%$ of initial value and shall not exceed the specification value
	Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi) ft/sec												
SMD	50	11	Half-sine	11.3													
Lead	50	11	Half-sine	11.3													
3 shocks in each direction along 3 perpendicular axes (18 shocks).																	
Solderability	Method B1, 4 Hrs at 155°C dry heat at $255^{\circ}\text{C} \pm 5^{\circ}\text{C}$ Test Time: 5 +0/-0.5 seconds. Method D category 3. (steam aging 8 hours $\pm 15\text{min}$) at $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ Test Time: 30+0/-0.5 seconds.	More than 95% of the terminal electrode should be covered with solder.															
Resistance to Soldering Heat	Solder temperature: $260 \pm 5^{\circ}\text{C}$ for 10 seconds Temperature ramp/immersion and emersion rate $25\text{mm/s} \pm 6\text{ mm/s}$. Completely cover the termination. Number of cycles: 1 heat cycle	Appearance: No damage Impedance: within $\pm 15\%$ of initial value Inductance: within $\pm 10\%$ of initial value Q: Shall not exceed the specification value RDC: within $\pm 15\%$ of initial value and shall not exceed the specification value															
Vibration	Oscillation Frequency: 10~2K~10 Hz for 20 minutes Total Amplitude: $1.52\text{mm} \pm 10\%$ Testing Time: 12 hours (20 minutes, 12 cycles each of 3 orientations)	Appearance: No damage Impedance: within $\pm 15\%$ of initial value Inductance: within $\pm 10\%$ of initial value Q: Shall not exceed the specification value RDC: within $\pm 15\%$ of initial value and shall not exceed the specification value															
Load Humidity	Humidity: $85 \pm 2\%$ R.H. Temperature: $85^{\circ}\text{C} \pm 2^{\circ}\text{C}$ Duration: 1000Hrs Min at 100% rated current Measured at Room Temperature after $24 \pm 2\text{hrs}$	Appearance: No damage Impedance: within $\pm 15\%$ of initial value Inductance: within $\pm 10\%$ of initial value Q: Shall not exceed the specification value RDC: within $\pm 15\%$ of initial value and shall not exceed the specification value															
Life Test	Temperature: $125 \pm 2^{\circ}\text{C}$ Duration: 1000Hrs Min. with 100% rated current Measured at Room Temperature after $24 \pm 2\text{Hrs}$																
Thermal Shock	Temperature: $-40 \sim 125^{\circ}\text{C}$ Dwell Time: 15minutes, Transfer Time: 20seconds Max Number of Cycles: 300cycles Measured at room temperature after placing for $24 \pm 2\text{hrs}$																
Terminal Strength	Component mounted on a PCB apply a force to the side of a device being tested. $> 0.805\text{inch}$ (2012mm): 1Kg, $\leq 0.805\text{inch}$ (2012mm): 0.5Kg Duration 60 +1 seconds. The force shall be applied gradually as not to shock the component being tested.		Appearance : No damage														
Board Flex	Place the 100x40mm FR4 board into a fixture with the component facing down. Apply a force which will bend the board: $\geq 0.805\text{in}$ (2012mm): 1.2mm $< 0.805\text{in}$ (2012mm): 0.8mm Duration: 10 seconds. The Force is to be applied only once to the board		Appearance : No damage														
Moisture Resistance	1. Baked at 50°C for 25hrs, measure at room temp after 4hrs. 2. Raise temperature to $65 \pm 2^{\circ}\text{C}$ 90-100%RH in 2.5hrs, 3. Keep at 65°C for 3 hours, cool down to 25°C in 2.5hrs. 4. Raise temperature to $65 \pm 2^{\circ}\text{C}$ 90-100%RH in 2.5hrs 5. Keep at 65°C for 3hrs, cool down to 25°C in 2.5hrs 6. Keep at 25°C for 2hrs then keep at -10°C for 3hrs 7. Keep at 25°C 80-100%RH for 15min, Vibrate at the frequency of 10 to 55 Hz to 10 Hz, Measure at room temperature after 1~2 hrs.	Appearance: No damage Impedance: within $\pm 15\%$ of initial value Inductance: within $\pm 10\%$ of initial value Q: Shall not exceed the specification value RDC: within $\pm 15\%$ of initial value and shall not exceed the specification value															

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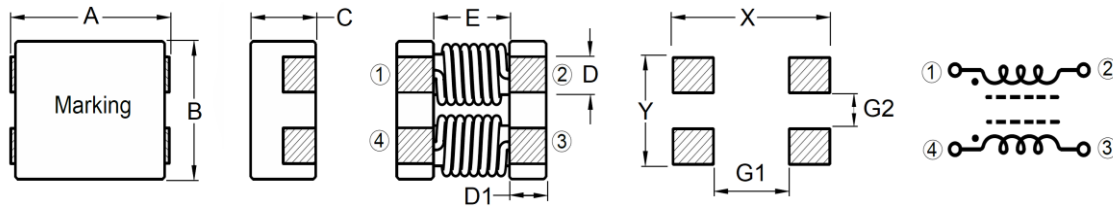
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DIMENSIONS – SIC-41 Series



Unit: mm

Size Code	A ±0.2	B ±0.2	C ±0.2	D ±0.1	D1 ±0.1	E Typ	X	Y	G1	G2
04 (0504)	1.2	1.00	0.9	0.35	0.35	0.5	1.5	1.2	0.6	0.3
03 (0603)	1.6	0.85	1.1	0.30	0.30	1.0	2.3	0.75	0.6	0.25
05 (0805)	2.0	1.20	1.2	0.50	0.50	1.0	2.6	1.25	1.1	0.45
06 (1206)	3.2	1.60	2.0	0.50	0.50	2.2	3.7	1.6	1.9	0.4
10 (1210)	3.2	2.50	2.2	0.80	0.90	1.4	4.4	3.5	1.6	0.6
12 (1812)	4.5	3.20	2.8	1.00	1.20	2.1	4.8	3.8	2.5	0.7

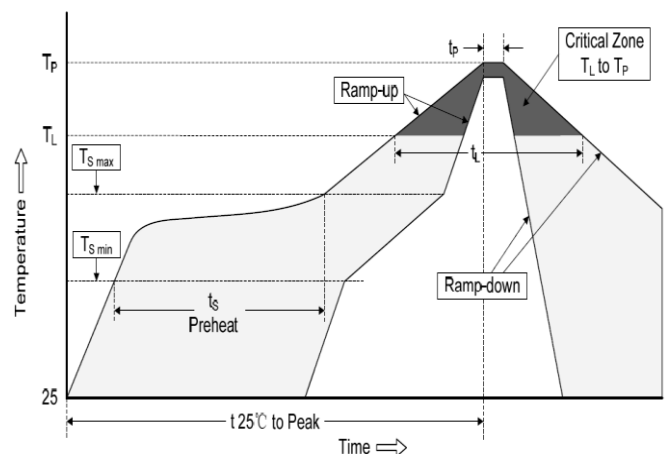


Unit: mm

Size Code	A ±0.5	B ±0.5	C Max	D	D1	E Typ	X	Y	G1	G2
121	12	10.8	6.4	2.7 ±0.2	2.5 ±0.2	7.0	12.2	8.1	6.8	2.3
70F	7.0	6.00	3.8	1.5 ±0.5	1.7 ±0.5	3.5	9.0	4.5	4.0	1.5
70C	7.0	6.00	3.8	1.5 Typ	1.7 Typ	3.5	9.0	4.5	4.0	1.5
907	9.0	7.00	4.8	1.5 ±0.2	1.7 ±0.2	5.7	11	5.0	5.0	1.5

RECOMMENDED SOLDERING PROFILES

Reflow Condition		
Pre Heat	Temp. Min $T_{s(min)}$	150°C
	Temp. Max $T_{s(max)}$	200°C
	Time (min. to max.) (t_s)	60 ~120 seconds
Average ramp up rate (Liquidus Temperature) (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L (Ramp-up rate)		3°C/second max
Reflow	Temp. (T_L)	217°C
	Time (min. to max.) (t_L)	60 ~150 seconds
Peak Temperature (T_P)		See table below
Time within 5°C of actual peak Temperature (t_p)		10 seconds max
Ramp-down Rate		6°C/second max
Reflow Times		3 times max



Peak Temperature (T_P)			
Volume	< 350mm ³	350-2000mm ³	> 2000mm ³
Thickness < 1.6mm	260°C	260°C	260°C
Thickness 1.6-2.5mm	260°C	250°C	245°C
Thickness ≥ 2.5mm	250°C	245°C	245°C

*Specifications subject to change without notice